

Title (en)

APPARATUS AND METHODS FOR CONTINUOUSLY DEPOSITING A PATTERN OF MATERIAL ONTO A SUBSTRATE

Title (de)

VORRICHTUNG UND VERFAHREN ZUR KONTINUIERLICHEN AUFTRAGUNG EINER MATERIALSTRUKTUR AUF EIN SUBSTRAT

Title (fr)

PROCEDE ET DISPOSITIF DE DEPOT CONTINU DE MOTIF DE MATERIAU SUR UN SUBSTRAT

Publication

EP 1902601 A2 20080326 (EN)

Application

EP 06787025 A 20060711

Priority

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- US 17941805 A 20050712

Abstract (en)

[origin: WO2007008992A2] A pattern of material is continuously deposited onto a substrate. The substrate and a mask are continuously brought together over a portion of a drum where a deposition source emits material. The mask includes apertures that form a pattern, and the material from the deposition source passes through the pattern of the mask and collects onto the substrate to form the pattern of material. The elongation and the transverse position of the substrate and the mask may be controlled. Pattern elements of the substrate and of the mask may be sensed in order to adjust the elongation and/or the transverse position of the substrate and/or mask to maintain a precise registration. Furthermore, the apertures may have a least dimension on the order of 100 microns or less to thereby create features on the substrate having least dimensions on the order of 100 microns or less.

IPC 8 full level

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